

pSEMI MATERIAL DECLARATION FORM

Product:	PE42422
Ordering Codes:	PE42422MLAA-Z
Description:	UltraCMOS® SPDT RF Switch, 5 – 6000 MHz
Package:	12 L 2X2 QFN
Environmental Compliance	EU RoHS 2 Directive 2011/65/EC, REACH - EU ECHA SVHC, Arsenic Free, JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
Lead Finish	NiPdAu
Availability	Now

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Aluminum oxide	1344-28-1	0.542130	7.70%	77,017.21
Die	Aluminum	7429-90-5	0.001649	0.02%	234.27
Die	Silicon	7440-21-3	0.000110	0.00%	15.62
Die	Arsenic*	7440-38-2	0.000001	0.00%	0.08
Die	Boron*	7440-42-8	0.000000	0.00%	0.01
Die	Phosphorous*	7723-14-0	0.000002	0.00%	0.31
Die	Titanium	7440-32-6	0.000275	0.00%	39.04
Die	Tungsten	7440-33-7	0.005497	0.08%	780.90
Die	Cobalt	7440-48-4	0.000011	0.00%	1.56
Die	Copper	7440-50-8	0.000004	0.00%	0.62
LeadFrame	Copper	7440-50-8	2.764500	39.27%	392,736.04
LeadFrame	Nickel	7440-02-0	0.026800	0.38%	3,807.32
LeadFrame	Iron	7439-89-6	0.066600	0.95%	9,461.47
LeadFrame	Zinc	7440-66-6	0.003400	0.05%	483.02
LeadFrame	Phosphorus	7723-14-0	0.000900	0.01%	127.86
LeadFrame	Palladium	7440-05-3	0.002100	0.03%	298.33
LeadFrame	Gold	7440-57-5	0.000000	0.00%	0.00
Die Attach	Silver (Ag)	7440-22-4	0.050900	0.72%	7,231.06
Die Attach	Epoxy Resin	9003-36-5	0.012700	0.18%	1,804.21
Die Attach	t-Butyl phenyl glycidyl ether	3101-60-8	0.005300	0.08%	752.94
Die Attach	Phenolic hardener	92-88-6	0.001100	0.02%	156.27
Die Attach	Butyl cellosolve acetate	112-07-2	0.000700	0.01%	99.44
Gold Wire	Gold	7440-57-5	0.080500	1.14%	11,436.16
Mold Compound	Silica Fused	60676-86-0	3.185500	45.25%	452,545.00
Mold Compound	Epoxy Resin	Trade secret	0.139000	1.97%	19,746.90
Mold Compound	Phenol Resin	Trade secret	0.139000	1.97%	19,746.90
Mold Compound	Carbon Black	1333-86-4	0.010400	0.15%	1,477.47
Total Weight (mg)			7.039079	100.00%	1,000,000

